



Material Content Data Sheet



Sales Product Name		BSC066N06NS		Issued		19. July 2018		
MA#		MA001075816						
Package		PG-TDSON-8-6		Weight*		118.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.385	0.33	0.33	3256	3256
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		320	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.97	32.01	319625	320041
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	387	387
encapsulation	organic material	carbon black	1333-86-4	0.088	0.07		745	
	plastics	epoxy resin	-	6.252	5.29		52921	
	inorganic material	silicondioxide	60676-86-0	37.690	31.90	37.26	319018	372684
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12287	12287
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1401	1401
solder	noble metal	silver	7440-22-4	0.015	0.01		127	
	non noble metal	tin	7440-31-5	0.012	0.01		102	
	non noble metal	lead	7439-92-1	0.573	0.48	0.50	4846	5075
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.58	9.59	95816	95941
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		189	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	copper	7440-50-8	22.292	18.87	18.90	188682	188928
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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